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colour inside

Semiconductor devices –
Part 5-6: Optoelectronic devices – Light emitting diodes

INTERNATIONAL
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COMMISSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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SEMICONDUCTOR DEVICES –

Part 5-6: Optoelectronic devices – Light emitting diodes

FOREWORD

1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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This redline version of the official IEC Standard allows the user to identify the changes made to the previous edition IEC 60747-5-6:2016. A vertical bar appears in the margin wherever a change has been made. Additions are in green text, deletions are in strikethrough red text.

IEC 60747-5-6 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices. It is an International Standard.

This second edition cancels and replaces the first edition published in 2016. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) ultraviolet-emitting diodes (UV LED) and their related technical contents were added;
b) power efficiency (η_{PE}) as part of electrical and optical characteristics were added;
c) new measuring methods related to thermal resistance were added;
d) hydrogen sulphide corrosion test was added to quality evaluation;
e) some standards were added to the bibliography.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47E/745/FDIS	47E/752/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

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SEMICONDUCTOR DEVICES –

Part 5-6: Optoelectronic devices – Light emitting diodes

1 Scope

This part of IEC 60747 specifies the terminology, the essential ratings and characteristics, the measuring methods and the quality evaluations of light emitting diodes (LEDs) for general industrial applications such as signals, controllers, sensors, etc.

LEDs for lighting applications are out of the scope of this part of IEC 60747.

LEDs are classified as follows:

a) LED package;
b) LED flat illuminator;
c) LED numeric display and alpha-numeric display;
d) LED dot-matrix display;
e) ~~I LED (~~infrared-emitting diode (IR LED);
f) ultraviolet-emitting diode (UV LED).

LEDs with a heat spreader or having a terminal geometry that performs the function of a heat spreader are within the scope of this part of IEC 60747.

An integration of LEDs and controlgears, integrated LED modules, semi-integrated LED modules, integrated LED lamps or semi-integrated LED lamps, are out of the scope of this part of IEC 60747.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60051 (all parts), *Direct acting indicating analogue electrical measuring instruments and their accessories*

IEC 60068-2-17, *Basic environmental testing procedures – Part 2-17: Tests – Test Q: Sealing*

IEC 60068-2-30, *Environmental testing – Part 2-30: Tests – Test Db: Damp heat, cyclic (12 h + 12 h cycle)*

IEC 60747-5-13, *Semiconductor devices – Part 5-13: Optoelectronic devices – Hydrogen sulphide corrosion test for LED packages*

IEC 60749-6, *Semiconductor devices – Mechanical and climatic test methods – Part 6: Storage at high temperature*

IEC 60749-10, *Semiconductor devices – Mechanical and climatic test methods – Part 10: Mechanical shock*

IEC 60749-12, *Semiconductor devices – Mechanical and climatic test methods – Part 12: Vibration, variable frequency*

IEC 60749-14, *Semiconductor devices – Mechanical and climatic test methods – Part 14: Robustness of terminations (lead integrity)*

IEC 60749-15, *Semiconductor devices – Mechanical and climatic test methods – Part 15: Resistance to soldering temperature for through-hole mounted devices*

IEC 60749-20, *Semiconductor devices – Mechanical and climatic test methods – Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat*

IEC 60749-21, *Semiconductor devices – Mechanical and climatic test methods – Part 21: Solderability*

IEC 60749-24, *Semiconductor devices – Mechanical and climatic test methods – Part 24: Accelerated moisture resistance – Unbiased HAST*

IEC 60749-25, *Semiconductor devices – Mechanical and climatic test methods – Part 25: Temperature cycling*

IEC 60749-36, *Semiconductor devices – Mechanical and climatic test methods – Part 36: Acceleration, steady state*

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Part 5-6: Optoelectronic devices – Light emitting diodes

IEC 60747-5-6:2021-07(en)

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